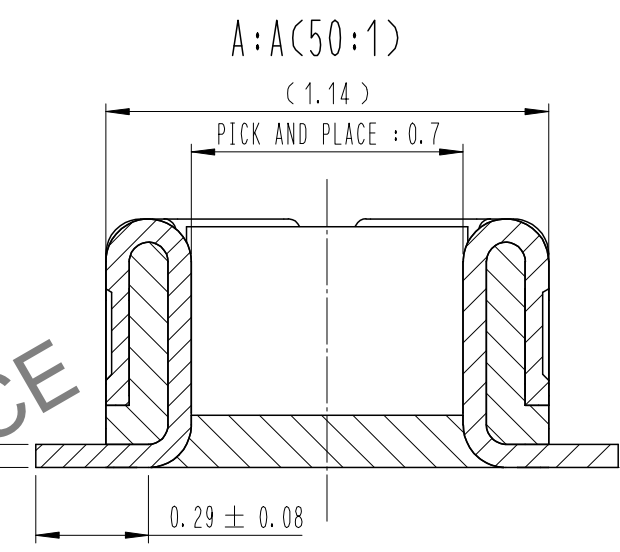
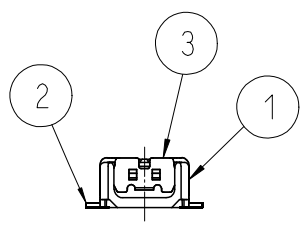
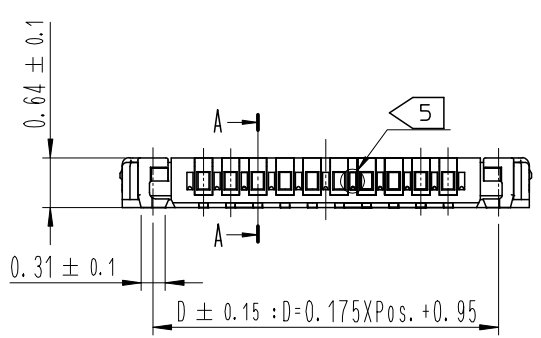
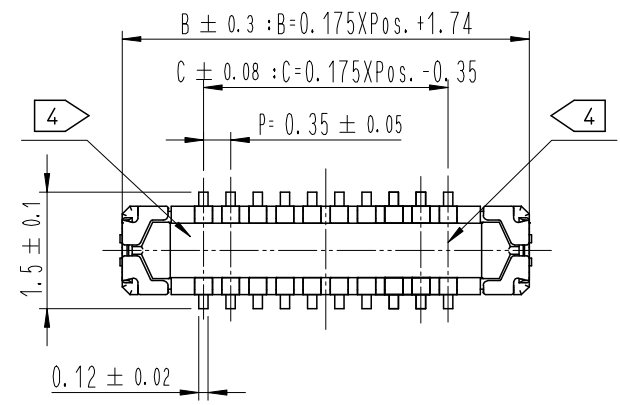
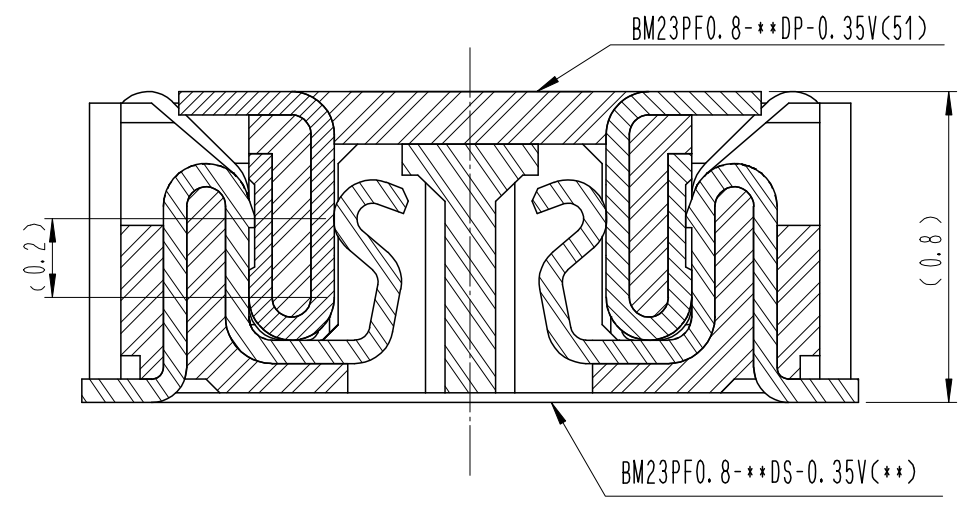


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COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
2	RE-6-0742	LYJ		JHW	16. 09 . 27	3	RE-6-1784	PSH		JHW	20. 04 . 09
3	RE-6-0806	MSH		JHW	17. 01 . 05						
1	RE-6-1137	KBJ		JHW	19. 02 . 14						



ENGAGEMENT FIGURE (50:1)



PART No.	CODE No.	POS.	B	C	D
BM23PF0.8-10DP-0.35V(51)	-	10	3.49	1.40	2.70
BM23PF0.8-14DP-0.35V(51)	-	14	4.19	2.10	3.40
BM23PF0.8-20DP-0.35V(51)	-	20	5.24	3.15	4.45
BM23PF0.8-24DP-0.35V(51)	-	24	5.94	3.85	5.15
BM23PF0.8-30DP-0.35V(51)	-	30	6.99	4.90	6.20
BM23PF0.8-40DP-0.35V(51)	-	40	8.74	6.65	7.95
BM23PF0.8-42DP-0.35V(51)	-	42	9.09	7.00	8.30
BM23PF0.8-44DP-0.35V(51)	-	44	9.44	7.35	8.65
BM23PF0.8-46DP-0.35V(51)	-	46	9.79	7.70	9.00
BM23PF0.8-50DP-0.35V(51)	-	50	10.49	8.40	9.70
BM23PF0.8-54DP-0.35V(51)	-	54	11.19	9.10	10.40
BM23PF0.8-60DP-0.35V(51)	-	60	12.24	10.15	11.45
BM23PF0.8-64DP-0.35V(51)	-	64	12.94	10.85	12.15

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
  - 2. CONTACT PLATING SPECIFICATIONS.  
CONTACT AREA : GOLD 0.05 μm MIN.  
SMT LEAD : GOLD 0.05 μm MIN.  
UNDER PLATING : NICKEL 1 μm MIN.  
( SURFACE : SEALING )
  - 3. METAL FITTING PLATING SPECIFICATIONS.  
SMT LEAD : GOLD 0.05 μm MIN.  
UNDERPLATING : NICKEL 1 μm MIN.  
( SURFACE : SEALING )
  - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
  - 5. A PART OF THE WALL COULD BE NOTCHED.

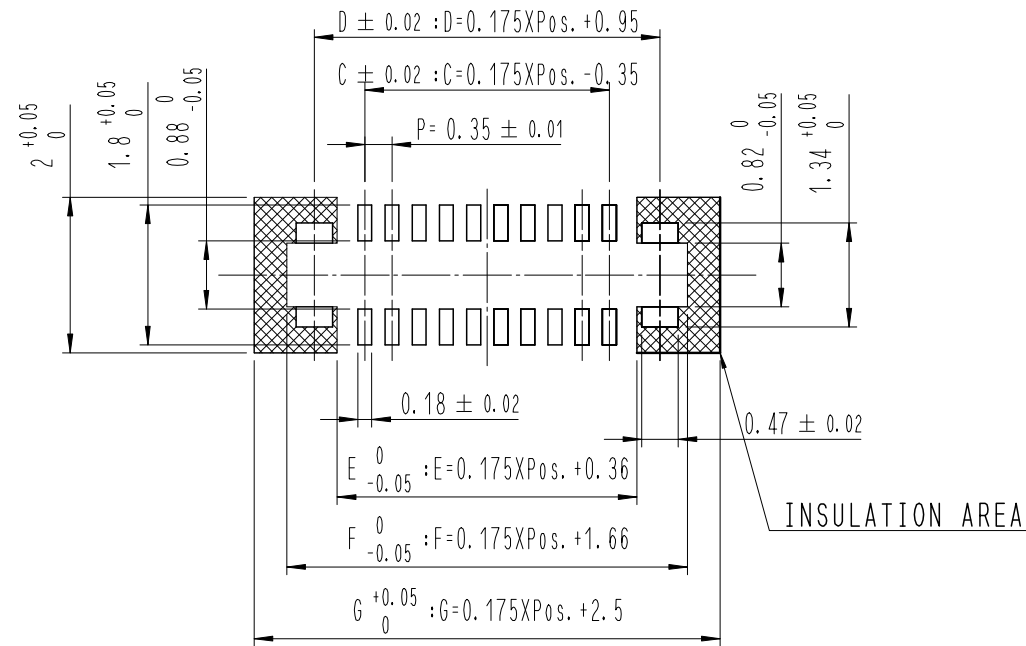
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
4	PS	CLEAR (EMBOSSED CARRIER TAPE)	7	PS	CLEAR(REINFORCEMENT COLLAR)
3	COOPER ALLOY		6	PS	BLACK (PLASTIC REEL)
2	COOPER ALLOY		5	POLYESTER	CLEAR (COVER TAPE)
1	LCP	UL94 V-0, BLACK			

REMARKS	DRAWN J. S. JANG 20.10.06	DESIGNED J. S. JANG 20.10.06	CHECKED H. W. JO 20.10.06	APPROVED H. W. JO 20.10.06	RELEASED 24.07.03
CODE NO. (OLD)	DRAWING NO. EDC3-*****		PART NO. BM23PF0.8-**-DP-0.35V(51)		
SCALE 10:1	UNITS mm		CODE NO. CL 66**-*****-51		1/3

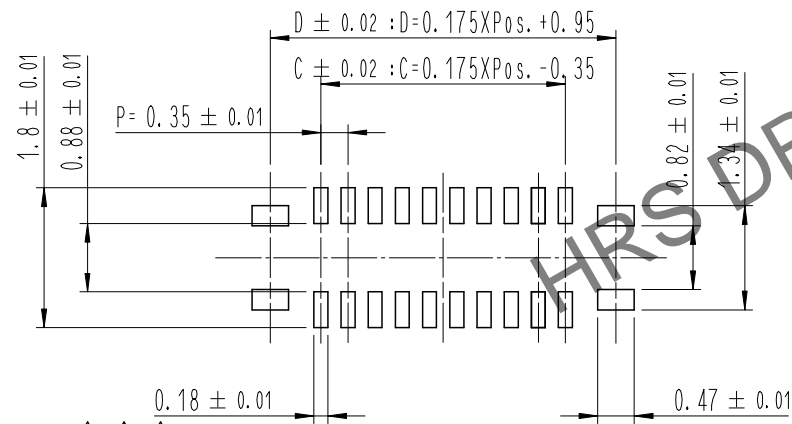
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7 RECOMMENDED PCB LAYOUT



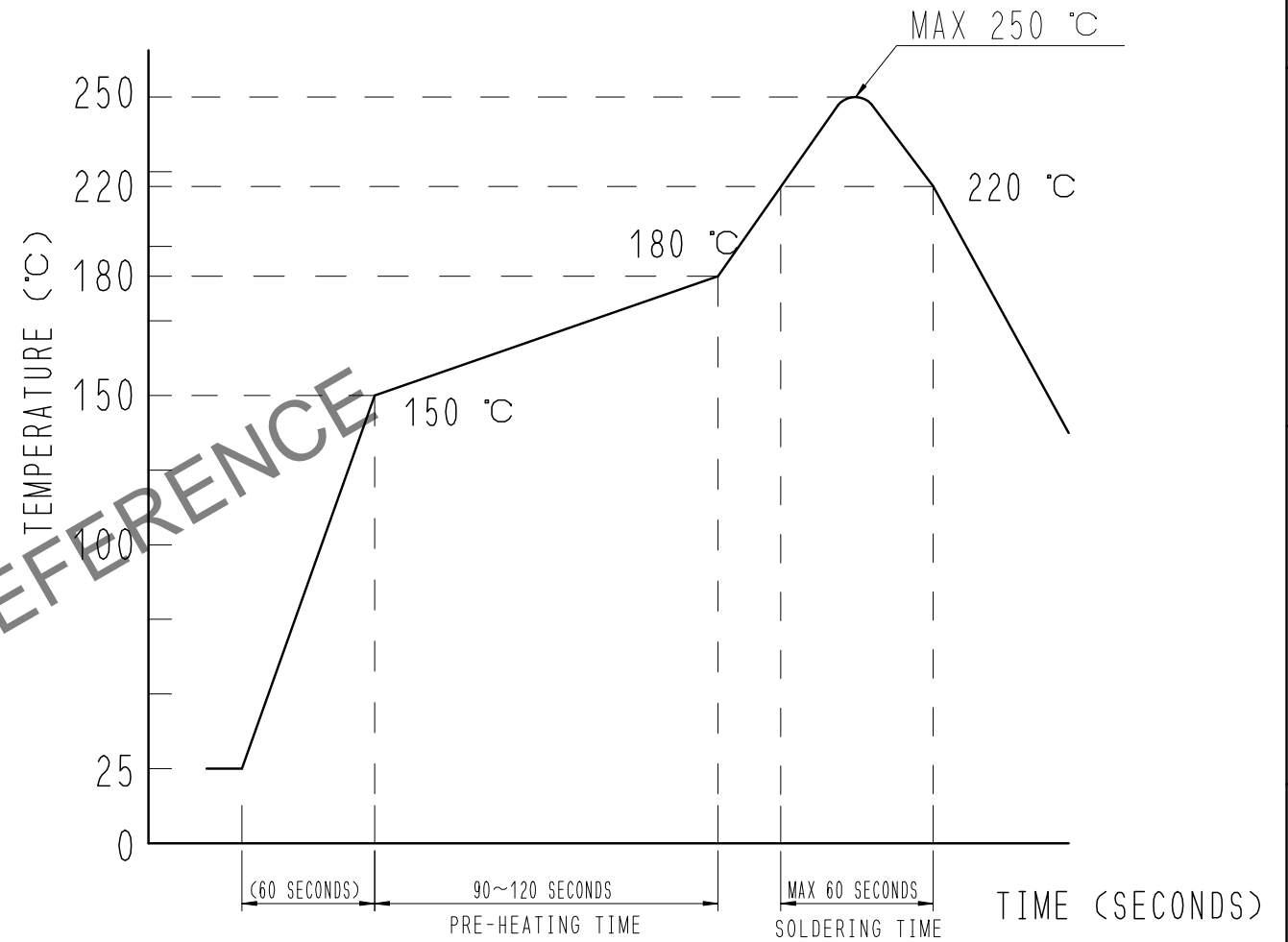
RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



POS.	C	D	E	F	G
10	1.40	2.70	2.11	3.41	4.25
14	2.10	3.40	2.81	4.11	4.95
20	3.15	4.45	3.86	5.16	6.00
24	3.85	5.15	4.56	5.86	6.70
30	4.90	6.20	5.61	6.91	7.75
40	6.65	7.95	7.36	8.66	9.50
42	7.00	8.30	7.71	9.01	9.85
44	7.35	8.65	8.06	9.36	10.20
46	7.70	9.00	8.41	9.71	10.55
50	8.40	9.70	9.11	10.41	11.25
54	9.10	10.40	9.81	11.11	11.95
60	10.15	11.45	10.86	12.16	13.00
64	10.85	12.15	11.56	12.86	13.70

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



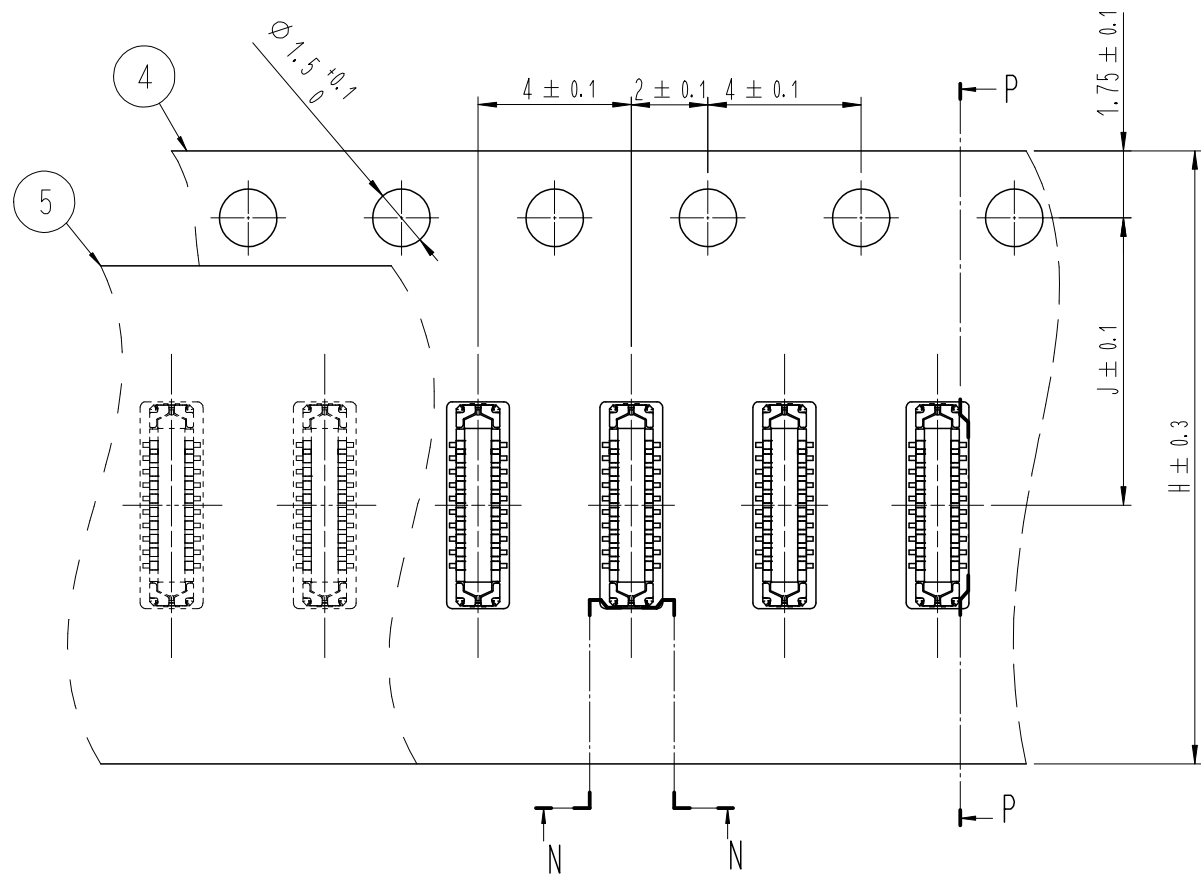
REFLOW METHOD: N<sub>2</sub> REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
 1) REFLOW TIME  
 DURATION ABOVE 220°C: 60 SEC MAX.  
 (PEAK TEMPERATURE: 250°C MAX)  
 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE (MIN): 150°C  
 PRE-HEAT TEMPERATURE (MAX): 180°C  
 PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

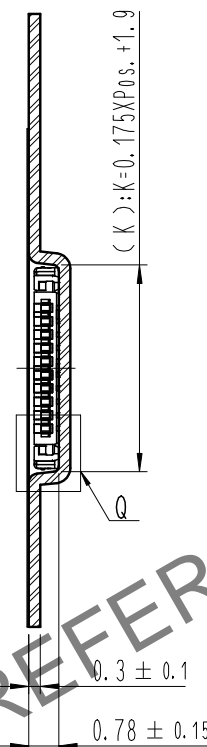
	DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-***DP-0.35V(51)	
	SCALE	10:1	CODE NO	CL 66**-*****-51	2/3
	UNITS	mm			

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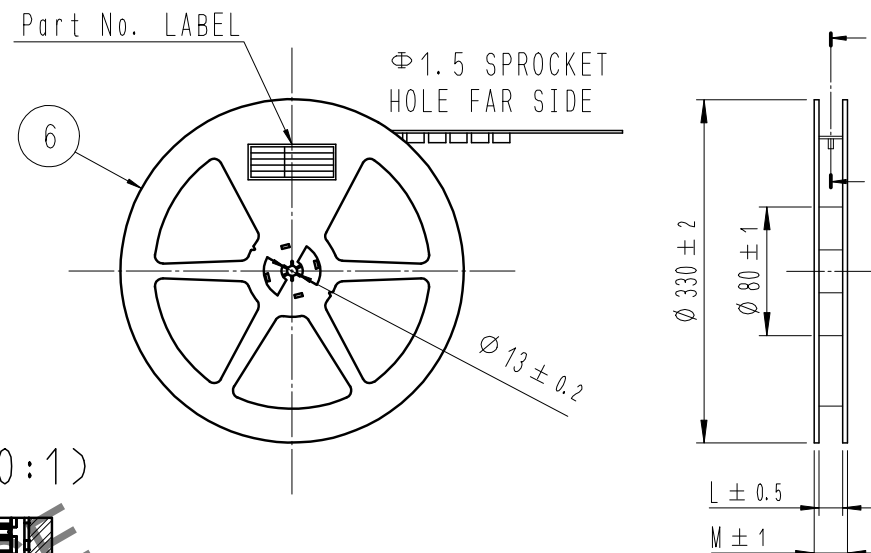
## EMBOSSED CARRIER TAPE PACKAGING (5:1)



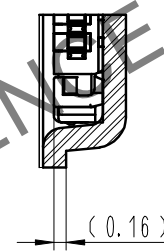
### P-P (5:1)



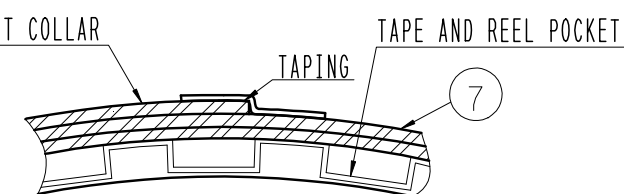
## STYLE AND DIMENTION OF REEL (FREE)



### Q (10:1)

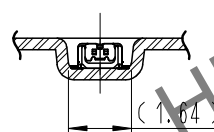


### E-E (FREE)



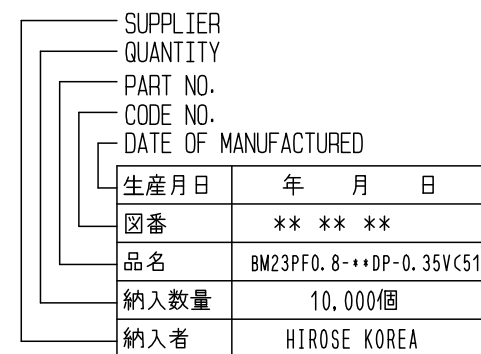
DIRECTION OF UNREELING

### N-N (5:1)



POS.	H	J	K	L	M
10	12	5.5	3.65	13.5	17.5
14	16	7.5	4.35	17.5	21.5
20	16	7.5	5.40	17.5	21.5
24	16	7.5	6.10	17.5	21.5
30	16	7.5	7.15	17.5	21.5
40	24	11.5	8.90	25.5	29.5
42	24	11.5	9.25	25.5	29.5
44	24	11.5	9.60	25.5	29.5
46	24	11.5	9.95	25.5	29.5
50	24	11.5	10.65	25.5	29.5
54	24	11.5	11.35	25.5	29.5
60	24	11.5	12.40	25.5	29.5
64	24	11.5	13.10	25.5	29.5

## DETAIL OF PART No. LABEL



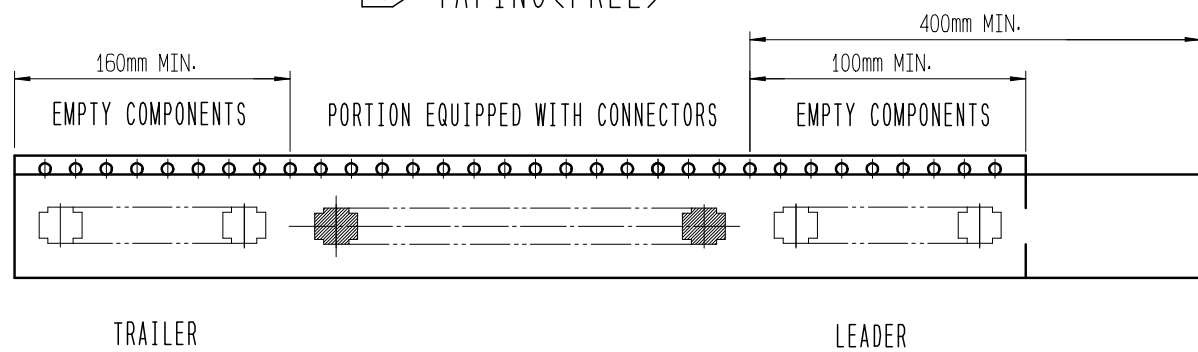
8 . PER REEL 10,000 CONNECTORS.

9 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

10 . REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

11 . AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

### 10 TAPING(FREE)



DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-**-DP-0.35V(51)
SCALE	10:1	CODE NO.	CL 66**-*****-51
UNITS	mm		